

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IQE013N04LM6CG	**Issued**	24. February 2022
MA#	MA005708500		
Package	PG-TTFN-9-1	**Weight***	43.33 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.896	2.07	2.07	20689	20689
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		76	
	non noble metal	zinc	7440-66-6	0.013	0.03		303	
	non noble metal	iron	7439-89-6	0.263	0.61		6064	
	non noble metal	copper	7440-50-8	10.669	24.62	25.27	246221	252664
encapsulation	organic material	carbon black	1333-86-4	0.029	0.07		668	
	plastics	epoxy resin	-	1.491	3.44		34413	
	inorganic material	silicondioxide	60676-86-0	12.957	29.90	33.41	299027	334108
leadfinish	non noble metal	tin	7440-31-5	0.474	1.09	1.09	10947	10947
plating	noble metal	silver	7440-22-4	0.296	0.68	0.68	6838	6838
solder	non noble metal	tin	7440-31-5	0.026	0.06		596	
	noble metal	silver	7440-22-4	0.032	0.07		745	
	non noble metal	lead	7439-92-1	1.234	2.85	2.98	28472	29813
heat sink clip	inorganic material	phosphorus	7723-14-0	0.004	0.01		102	
	non noble metal	iron	7439-89-6	0.015	0.03		340	
	non noble metal	copper	7440-50-8	14.697	33.93	33.97	339187	339629
clip attach	non noble metal	tin	7440-31-5	0.005	0.01		106	
	noble metal	silver	7440-22-4	0.006	0.01		133	
	non noble metal	lead	7439-92-1	0.220	0.51	0.53	5073	5312
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com